

ABSTRACT

The method for manufacturing an electronic device of the present invention includes at least: a step (1) of preparing a structure (100) provided with an adhesive film (50) provided with a base material layer (10), an adhesive resin layer (A) provided on a first surface (10A) side of the base material layer (10) and for temporarily fixing an electronic component (70), and an adhesive resin layer (B) provided on a second surface (10B) side of the base material layer (10) and in which an adhesive force is decreased by an external stimulus, an electronic component (70) attached to the adhesive resin layer (A) of the adhesive film (50), and a support substrate (80) attached to the adhesive resin layer (B) of the adhesive film (50); at least one step (2) selected from a step (2-1) of decreasing water content in the adhesive film (50) and a step (2-2) of decreasing water content in the structure (100); and a step (3) of sealing the electronic component (70) with a sealing material (60).